

NBVSBA011/D

2.5 V/3.3 V, LVPECL Voltage-Controlled Crystal Oscillator (VCXO) PureEdge™ Product Series

The NBVSBA011/D series voltage-controlled crystal oscillator (VCXO) devices are designed to meet today's requirements for 2.5 V and 3.3 V LVPECL clock generation applications. These devices use a high Q fundamental mode crystal and Phase Locked Loop (PLL) multiplier to provide a wide range of frequencies from 60 MHz to 700 MHz (factory configurable per user specifications) with a pullable range of ± 100 ppm and a frequency stability of ± 50 ppm. The silicon-based PureEdge™ products design provides users with exceptional frequency stability and reliability. They produce an ultra low jitter and phase noise LVPECL differential output.

The NBVSBA011/D series are members of ON Semiconductor's PureEdge™ clock family that provides accurate and precision clock generation solutions.

Available in the industry standard 5.0 x 7.0 x 1.8 mm and in a new 3.2 x 5.0 x 1.2 mm SMD (CLCC) package on 16 mm tape and reel in quantities of 1,000.

Features

- LVPECL Differential Output
- Operating Range: 2.5 V $\pm 5\%$, 3.3 V $\pm 10\%$
- Ultra Low Jitter and Phase Noise – 0.5 ps (12 kHz – 20 MHz)
- Factory Configurable Frequencies from 60 MHz to 700 MHz (see Standard Frequencies in the Ordering Information Table in page 6)
- Pullable Range Minimum of ± 100 ppm
- Orderable Frequency Stability of ± 20 ppm or ± 50 ppm
- Control Voltage with Positive Slope
- Voltage Control Linearity of $\pm 10\%$
- Uses High Q Fundamental Mode Crystal
- Hermetically Sealed Ceramic SMD Package
- These Devices are Pb-Free and RoHS Compliant

Applications

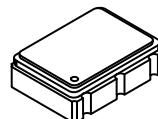
- Networking
- SONET
- 10 Gigabit Ethernet
- Networking Base Stations
- Broadcasting



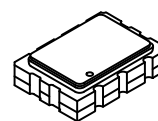
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MARKING DIAGRAM



6 PIN CLCC
LN SUFFIX
CASE 848AB



6 PIN CLCC
LU SUFFIX
CASE 848AC



NBVSBA011/D = NBVSBA011/D (± 50 ppm)
XXX.XXXX = Output Frequency (MHz)
AA = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

NBVSBAxxx Series

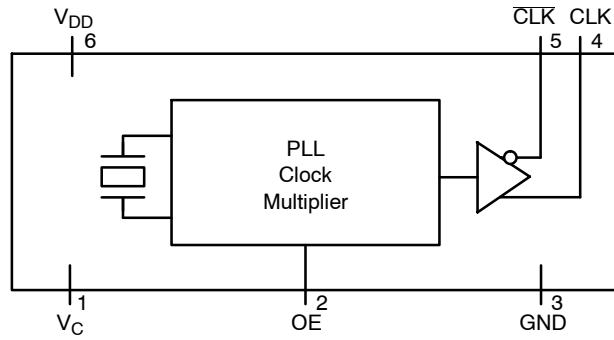


Figure 1. Simplified Logic Diagram

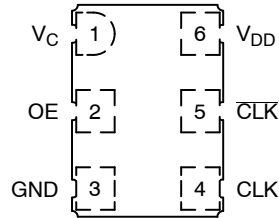


Figure 2. Pin Connections (Top View)

Table 1. PIN DESCRIPTION

Pin No.	Symbol	I/O	Description
1	V_C (Note 1)	Analog Input	Analog control voltage input pin that adjusts output oscillation frequency. $f_0 = V_C = 1.65 \text{ V}$
2	OE	LVTTTL/LVCMOS Control Input	Output Enable Pin. When left floating pin defaults to logic HIGH and output is active. See OE pin description Table 2.
3	GND	Power Supply	Ground at 0 V. Electrical and Case Ground.
4	CLK	LVPECL Output	Non-Inverted Clock Output. Typically loaded with 50Ω receiver termination resistor to $V_{TT} = V_{DD} - 2 \text{ V}$.
5	$\overline{\text{CLK}}$	LVPECL Output	Inverted Clock Output. Typically loaded with 50Ω receiver termination resistor to $V_{TT} = V_{DD} - 2 \text{ V}$.
6	V_{DD}	Power Supply	Positive Power Supply Voltage. Voltage should not exceed $2.5 \text{ V} \pm 5\%$ and $3.3 \text{ V} \pm 10\%$.

1. Control voltage has a positive slope with a linearity of $\pm 10\%$; $V_C = 1.65 \text{ V} \pm 1 \text{ V}$.

Table 2. OUTPUT ENABLE TRI-STATE FUNCTION

OE Pin	Output Pins
Open	Active
HIGH Level	Active
LOW Level	High Z

Table 3. ATTRIBUTES

Characteristic	Value
Internal Default State Resistor	$170 \text{ k}\Omega$
ESD Protection Human Body Model Machine Model	2 kV 200 V
Meets or Exceeds JEDEC Standard EIA/JESD78 IC Latchup Test	

2. For additional Moisture Sensitivity information, refer to Application Note AND8003/D.

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Table 4. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V_{DD}	Positive Power Supply	GND = 0 V		4.6	V
V_{IN}	Control Input (V_C and OE)		$V_{IN} \leq V_{DD} + 200 \text{ mV}$ $V_{IN} \geq \text{GND} - 200 \text{ mV}$		V
I_{out}	LVPECL Output Current	Continuous Surge		25 50	mA
T_A	Operating Temperature Range			-40 to +85	°C
T_{stg}	Storage Temperature Range			-55 to +120	°C
T_{sol}	Wave Solder	See Figure 4		260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 5. DC CHARACTERISTICS ($V_{DD} = 2.5 \text{ V} \pm 5\%$; $3.3 \text{ V} \pm 10\%$, GND = 0 V, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$) (Note 3)

Symbol	Characteristic	Conditions	Min.	Typ.	Max.	Units
I_{DD}	Power Supply Current			90	110	mA
V_{IH}	Input HIGH Voltage	OE	2000		V_{DD}	mV
V_{IL}	Input LOW Voltage	OE	GND - 200		800	mV
I_{IH}	Input HIGH Current	OE	-100		+100	μA
I_{IL}	Input LOW Current	OE	-100		+100	μA
V_{OH}	Output HIGH Voltage		$V_{DD} - 1195$		$V_{DD} - 945$	mV
V_{OL}	Output LOW Voltage		$V_{DD} - 1945$		$V_{DD} - 1600$	mV
V_{OUTPP}	Output Voltage Amplitude			700		mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

3. Measurement taken with outputs terminated with 50Ω to $V_{DD} - 2.0 \text{ V}$. See Figure 3.

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Table 6. AC CHARACTERISTICS ($V_{DD} = 2.5 \pm 5\%$, $V_{DD} = 3.3 \pm 10\%$, $GND = 0\text{ V}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)

Symbol	Characteristic	Conditions	Min.	Typ.	Max.	Units
f_{CLKOUT}	Output Clock Frequency	NBVSBA011		122.88		MHz
		NBVSBA027		148.50		
		NBVSBA018		155.52		
		NBVSBA017		156.25		
		NBVSBA015		200.00		
		NBVSBA024		622.08		
		NBVSBA026		644.53		
Δf	Frequency Stability	(Note 5)			± 50	ppm
$t_{jit}(\phi)$	RMS Phase Jitter	12 kHz to 20 MHz		0.5	0.9	ps
t_{jitter}	Cycle to Cycle, RMS	1000 Cycles		2	8	ps
	Cycle to Cycle, Peak-to-Peak	1000 Cycles		10	30	ps
	Period, RMS	10,000 Cycles		1	4	ps
	Period, Peak-to-Peak	10,000 Cycles		6	20	ps
$t_{OE/OD}$	Output Enable/Disable Time				200	ns
F_P	Crystal Pullability (Note 4)	$0 \leq V_C \leq 3.3\text{ V}$	± 100			ppm
$V_{C(bw)}$	Control Voltage Bandwidth	- 3 dB	20			KHz
t_{DUTY_CYCLE}	Output Clock Duty Cycle (Measured at Cross Point)		45	50	55	%
t_R	Output Rise Time (20% and 80%)			245	400	ps
t_F	Output Fall Time (80% and 20%)			245	400	ps
t_{start}	Start-up Time			1	5	ms
	Aging	1 st Year			3	ppm
		Every Year After 1 st			1	

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

4. Gain transfer is positive with a rate of 95 ppm/V.

5. Parameter guarantees 10 years of aging. Includes initial stability at 25°C, shock, vibration and first year aging.

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Table 7. PHASE NOISE PERFORMANCE

Parameter	Characteristic	Condition	011	027	018	017	015	024	026	Units
			122.88 MHz	148.50 MHz	155.52 MHz	156.25 MHz	200.00 MHz	622.08 MHz	644.53 MHz	
ϕ NOISE	Output Phase-Noise Performance	100 Hz offset	-90	-90	-90	-90	-87	-80	-86	dBc/Hz
		1 kHz offset	-118	-118	-116	-116	-114	-106	-107	dBc/Hz
		10 kHz offset	-127	-127	-126	-126	-125	-117	-116	dBc/Hz
		100 kHz offset	-127	-127	-126	-126	-125	-117	-116	dBc/Hz
		1 MHz offset	-134	-134	-134	-134	-132	-122	-125	dBc/Hz
		10 MHz offset	-160	-160	-160	-160	-158	-150	-150	dBc/Hz

Table 8. RELIABILITY COMPLIANCE

Parameter	Standard	Method
Shock	Mechanical	MIL-STD-833, Method 2002, Condition B
Solderability	Mechanical	MIL-STD-833, Method 2003
Vibration	Mechanical	MIL-STD-833, Method 2007, Condition A
Solvent Resistance	Mechanical	MIL-STD-202, Method 215
Thermal Shock	Environment	MIL-STD-833, Method 1011, Condition A
Moisture Level Sensitivity	Environment	MSL1 260°C per IPC/JEDEC J-STD-020D

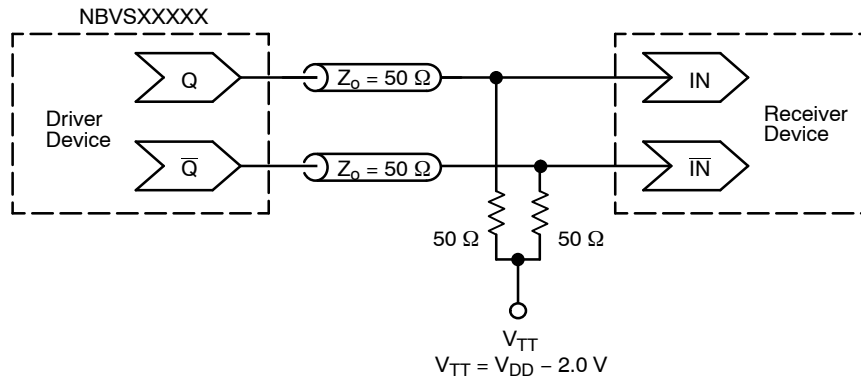


Figure 3. Typical Termination for Output Driver and Device Evaluation
(See Application Note AND8020/D – Termination of ECL Logic Devices.)

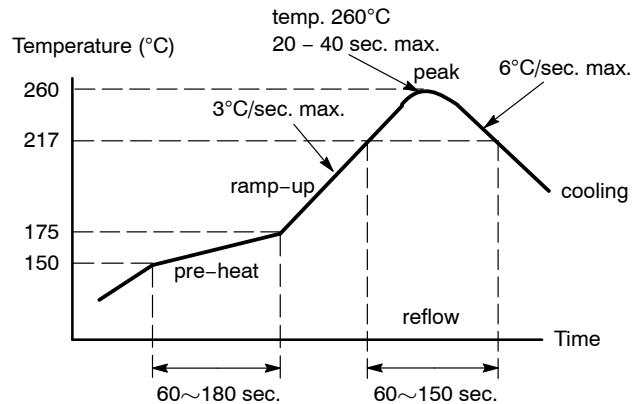


Figure 4. Recommended Reflow Soldering Profile

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Table 9. ORDERING INFORMATION

Device	Output Frequency (MHz)	Package	Shipping [†]
5.0 x 7.0 x 1.8 mm			
NBVSBA011LN1TAG	122.88	CLCC-6, Pb-Free	1000 / Tape & Reel
NBVSBA027LN1TAG	148.50	CLCC-6, Pb-Free	1000 / Tape & Reel
NBVSBA018LN1TAG	155.52	CLCC-6, Pb-Free	1000 / Tape & Reel
NBVSBA017LN1TAG	156.25	CLCC-6, Pb-Free	1000 / Tape & Reel
NBVSBA015LN1TAG	200.00	CLCC-6, Pb-Free	1000 / Tape & Reel
NBVSBA024LN1TAG	622.08	CLCC-6, Pb-Free	1000 / Tape & Reel
NBVSBA026LN1TAG	644.53	CLCC-6, Pb-Free	1000 / Tape & Reel
3.2 x 5.0 x 1.2 mm			
NBVSBA011LU1TAG*	122.88	CLCC-6, Pb-Free	1000 / Tape & Reel
NBVSBA027LU1TAG*	148.50	CLCC-6, Pb-Free	1000 / Tape & Reel
NBVSBA018LU1TAG*	155.52	CLCC-6, Pb-Free	1000 / Tape & Reel
NBVSBA017LU1TAG*	156.25	CLCC-6, Pb-Free	1000 / Tape & Reel
NBVSBA015LU1TAG*	200.00	CLCC-6, Pb-Free	1000 / Tape & Reel
NBVSBA024LU1TAG*	622.08	CLCC-6, Pb-Free	1000 / Tape & Reel
NBVSBA026LU1TAG*	644.53	CLCC-6, Pb-Free	1000 / Tape & Reel

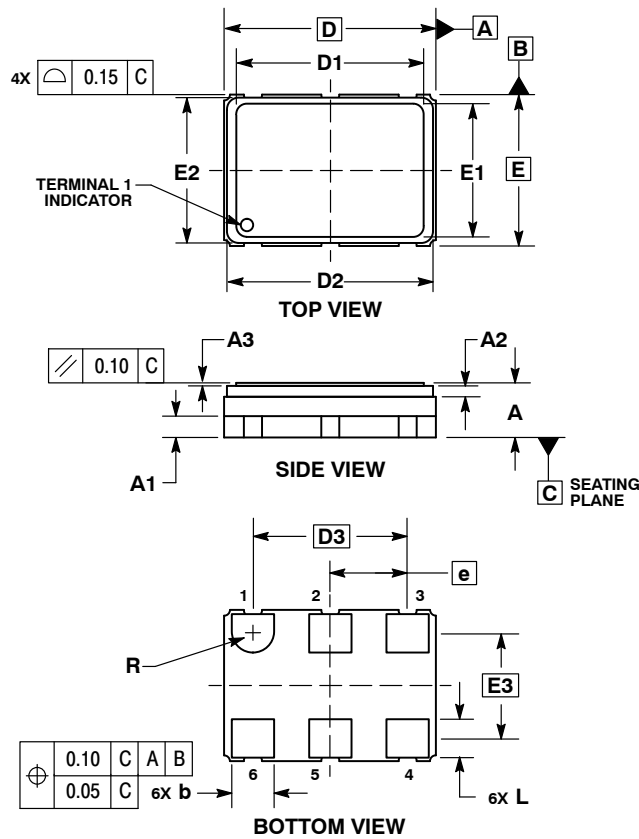
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and Reel Packaging Specification Brochure, BRD8011/D.

*Consult factory for availability.

NBVSBAxxx Series

PACKAGE DIMENSIONS

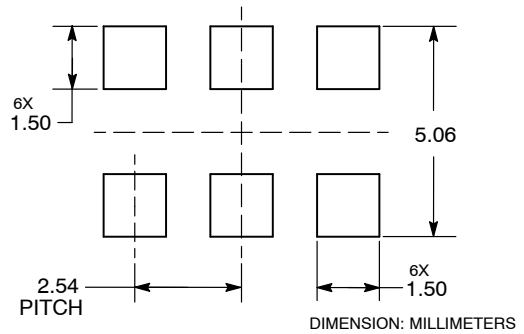
6 PIN CLCC, 7x5, 2.54P
CASE 848AB-01
ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	1.70	1.80	1.90
A1	0.70 REF		
A2	0.36 REF		
A3	0.08	0.10	0.12
b	1.30	1.40	1.50
D	7.00 BSC		
D1	6.17	6.20	6.23
D2	6.66	6.81	6.96
D3	5.08 BSC		
E	5.00 BSC		
E1	4.37	4.40	4.43
E2	4.65	4.80	4.95
E3	3.49 BSC		
e	2.54 BSC		
L	1.17	1.27	1.37
R	0.70 REF		

SOLDERING FOOTPRINT*

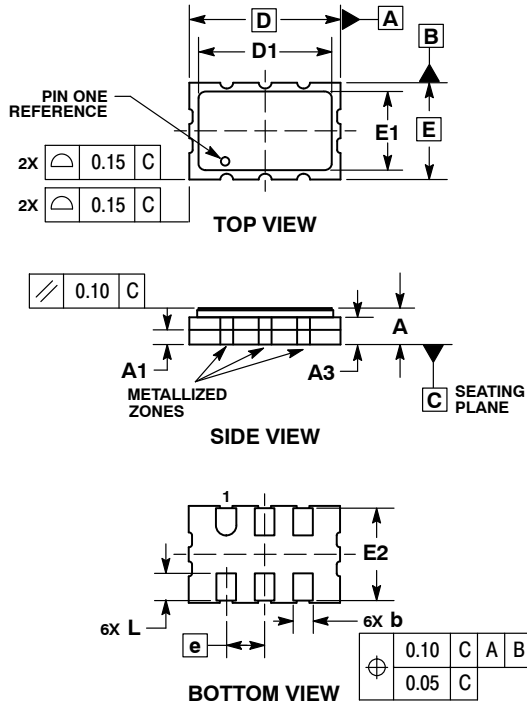


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PACKAGE DIMENSIONS

6 PIN CLCC, 5x3.2, 1.27P
CASE 848AC-01
ISSUE O

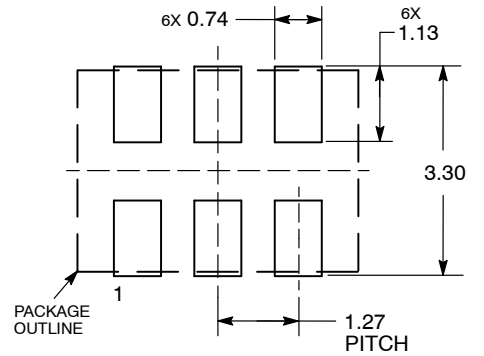


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

DIM	MIN	MAX
A	1.05	1.35
A1	0.35	0.65
A3	0.90 REF	
b	0.50	0.80
D	5.00 BSC	
D1	4.25	4.55
E	3.20 BSC	
E1	2.45	2.75
E2	2.90	3.20
e	1.27 BSC	
L	0.75	1.05

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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